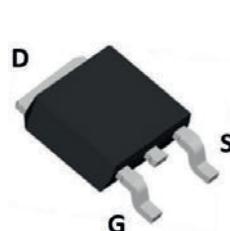
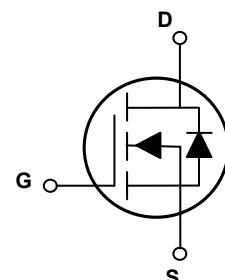


Main Product Characteristics

$V_{(BR)DSS}$	250V
$R_{DS(ON)}$	0.28Ω (Max.)
I_D	14A



TO-252 (DPAK)



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFD2514 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Parameter	Unit
Drain-Source Voltage	V_{DS}	250	V
Gate-to-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current, @ Steady-State ($T_C=25^\circ\text{C}$)	I_D	14	A
Continuous Drain Current, @ Steady-State ($T_C=100^\circ\text{C}$)		9.0	A
Pulsed Drain Current ¹	I_{DM}	56	A
Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	88	W
		0.71	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy	E_{AS}	240	mJ
Body Diode Reverse Voltage Slop	dv/dt	4.5	V/ns
MOS dv/dt Ruggedness	dv/dt	50	V/ns
Junction-to-Ambient (PCB Mounted, Steady-State)	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Junction-to-Case	$R_{\theta JC}$	1.42	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	T_J/T_{STG}	-55 to +150	$^\circ\text{C}$
Maximum Lead Temperature for Soldering Purposes	T_L	260	$^\circ\text{C}$

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	250	-	-	V
Drain-to-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=250\text{V}, V_{\text{GS}}=0\text{V}, T_C=25^\circ\text{C}$	-	-	1.0	μA
		$V_{\text{DS}}=200\text{V}, T_C=125^\circ\text{C}$	-	-	100	μA
Gate-to-Source Forward Leakage	I_{GSS}	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=30\text{V}$	-	-	100	nA
		$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=-30\text{V}$	-	-	-100	
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_D=7\text{A}$	-	0.224	0.28	Ω
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	3.0	-	4.6	V
Dynamic and Switching Characteristics						
Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, f=1\text{MHz}$	-	673	-	pF
Output Capacitance	C_{oss}		-	107	-	
Reverse Transfer Capacitance	C_{rss}		-	13	-	
Total Gate Charge ^{2,3}	Q_g	$I_D=14\text{A}, V_{\text{DS}}=200\text{V}, V_{\text{GS}}=10\text{V}$	-	18	-	nC
Gate-to-Source Charge ^{2,3}	Q_{gs}		-	7.8	-	
Gate-to-Drain ("Miller") Charge ^{2,3}	Q_{gd}		-	7.5	-	
Turn-on Delay Time ^{2,3}	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=125\text{V}, V_{\text{GS}}=10\text{V}, R_G=25\Omega, I_D=14\text{A}$	-	15	-	nS
Rise Time ^{2,3}	t_r		-	61	-	
Turn-Off Delay Time ^{2,3}	$t_{\text{d}(\text{off})}$		-	25	-	
Fall Time ^{2,3}	t_f		-	26	-	
Gate Resistance	R_g	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, f=1\text{MHz}$	-	3.1	-	Ω
Source-Drain Ratings and Characteristics						
Continuous Source Current (Body Diode)	I_s	$T_C=25^\circ\text{C}$, MOSFET symbol showing the integral reverse p-n junction diode.	-	-	14	A
Diode Pulse Current	I_{SM}		-	-	56	A
Diode Forward Voltage	V_{SD}	$I_s=4.0\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.3	V
Reverse Recovery Time	T_{rr}	$I_s=14\text{A}, V_{\text{GS}}=0\text{V}, dI_F/dt=100\text{A/us}$	-	203	-	nS
Reverse Recovery Charge	Q_{rr}		-	1.5	-	uC

Notes:

1. Pulse width limited by maximum junction temperature.
2. Pulse test : Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

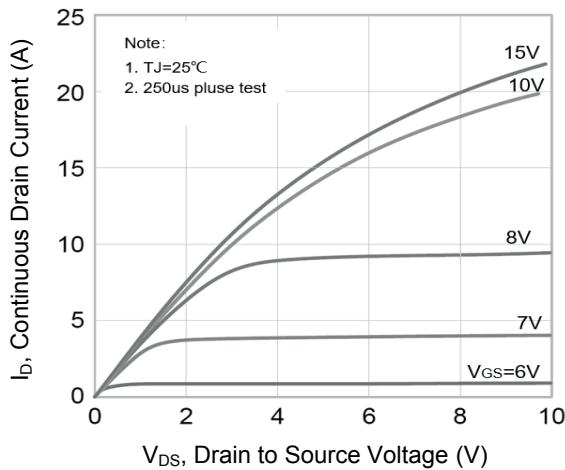


Figure 1. Output Characteristics

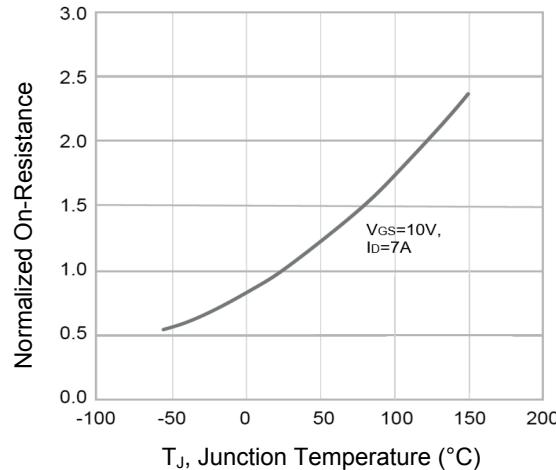


Figure 2. Normalized $R_{DS(ON)}$ vs. T_J

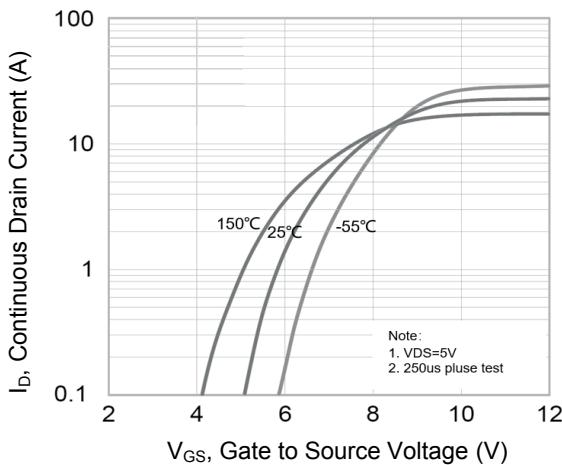


Figure 3. Transfer Characteristics

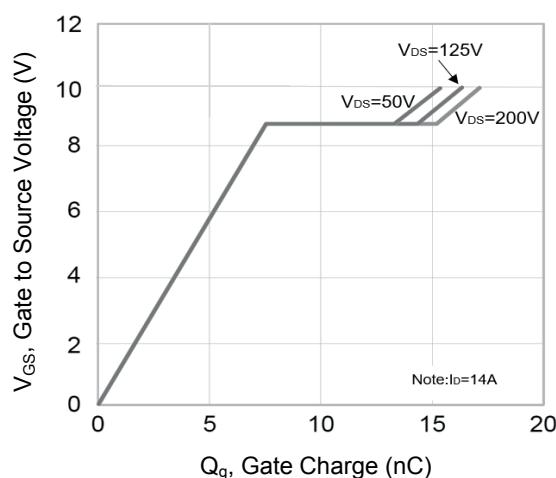


Figure 4. Gate Charge Waveform

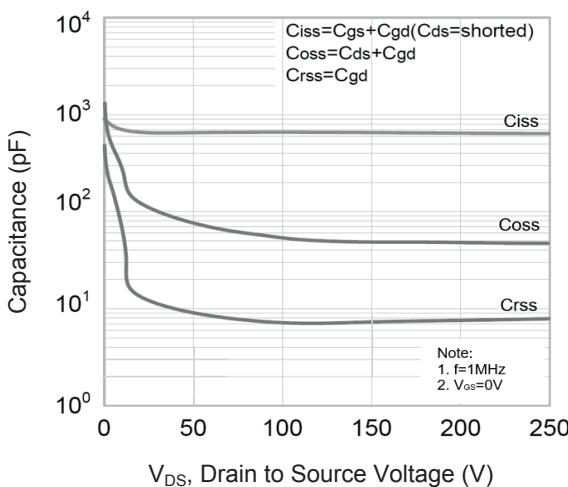


Figure 5. Capacitance Characteristics

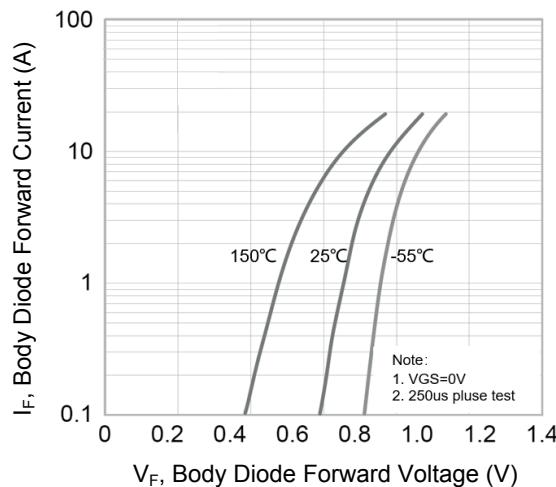
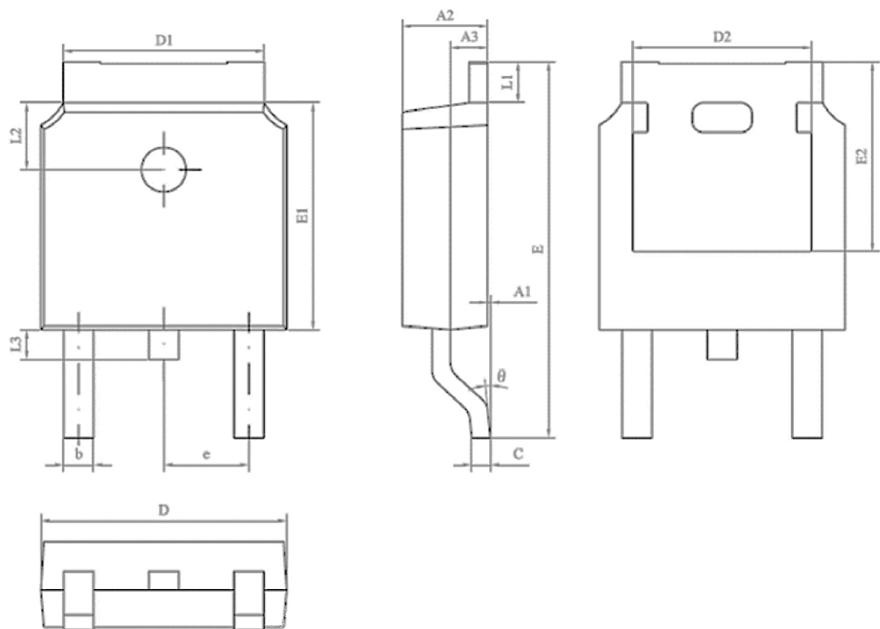


Figure 6. Body Diode Characteristics

Package Outline Dimensions TO-252 (DPAK)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	0.00	0.10	0.000	0.004
A2	2.20	2.40	0.087	0.094
A3	0.09	1.10	0.004	0.043
b	0.75	0.85	0.030	0.033
C	0.50	0.60	0.020	0.024
D	6.50	6.70	0.256	0.264
D1	5.30	5.50	0.209	0.217
D2	4.70	4.90	0.185	0.193
E	9.90	10.30	0.390	0.406
E1	6.00	6.20	0.236	0.244
E2	5.00	5.20	0.197	0.205
e	2.20	2.40	0.087	0.094
L1	0.90	1.25	0.035	0.049
L2	1.70	1.90	0.067	0.075
L3	0.60	1.00	0.024	0.039
θ	0°	8°	0°	8°

Order Information

Device	Package	Marking	Carrier	Quantity
GSFD2514	TO-252 (DPAK)	D2514	Tape & Reel	2,500pcs / Reel